

RELIABILITY REPORT FOR MAX9830AETA+ PLASTIC ENCAPSULATED DEVICES

February 5, 2010

# MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR. SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering



#### Conclusion

The MAX9830AETA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

# Table of Contents

IDevice Description	VQuality Assurance Information
IIManufacturing Information	VIReliability Evaluation

- III. ......Packaging Information
- .....Attachments

VI. ......Reliability Evaluation

# I. Device Description

A. General

The MAX9830 mono 2W Class D amplifier provides Class AB audio performance with Class D efficiency. Active emissions limiting edge rate and overshoot control circuitry greatly reduces EMI. A patented filterless spread-spectrum modulation scheme eliminates the need for output filtering found in traditional Class D devices. These features reduce application component count. The MAX9830's industry-leading 1.6mA at 5V, 1.2mA at 3.6V, quiescent current extends battery life in portable applications. The MAX9830 is available in an 8-pin TDFN (2mm x 2mm x 0.8mm) and is specified over the extended -40°C to +85°C temperature range.



#### II. Manufacturing Information

A. Description/Function:	Mono 2W Class D Amplifier
B. Process:	S18
C. Number of Device Transistors:	1818
D. Fabrication Location:	California
E. Assembly Location:	Thailand
F. Date of Initial Production:	7/26/2009

# III. Packaging Information

A. Package Type:	8-pin TDFN 2x2
B. Lead Frame:	Copper Alloy
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3315
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jc:	10.8°C/W
K. Multi Layer Theta Ja:	83.9°C/W
L. Multi Layer Theta Jc:	36.6°C/W

## IV. Die Information

A. Dimensions:	29.5 X 29.5 mils
B. Passivation:	$Si_3N_4/SiO_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.18µm
F. Minimum Metal Spacing:	0.18µm
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw



#### V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

# VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (  $\lambda$ ) is calculated as follows:

 $\lambda = \underbrace{1}_{\text{MTTF}} = \underbrace{1.83}_{192 \text{ x} 4340 \text{ x} 76 \text{ x} 2}_{(\text{where } 4340 \text{ = Temperature Acceleration factor assuming an activation energy of 0.8eV)}$  $\lambda = 14.1 \text{ x} 10^{-9}$  $\lambda = 14.1 \text{ F.I.T.} (60\% \text{ confidence level @ 25°C})$ 

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S18 Process results in a FIT Rate of 0.40 @ 25C and 6.96 @ 55C (0.8 eV, 60% UCL)

## B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

#### C. E.S.D. and Latch-Up Testing

The AX06 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltager per JESD78.



# Table 1 Reliability Evaluation Test Results

## MAX9830AETA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	
Static Life Test	(Note 1)				
	Ta = 135°C	DC Parameters	76	0	
	Biased	& functionality			
	Time = 192 hrs.				
Moisture Testing	(Note 2)				
HAST	Ta = 130°C	DC Parameters	77	0	
	RH = 85%	& functionality			
	Biased				
	Time = 96hrs.				
Mechanical Stres	ss (Note 2)				
Temperature	-65°C/150°C	DC Parameters	77	0	
Cycle	1000 Cycles	& functionality			
-	Method 1010				

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data